

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE

**REQUEST FOR CONTINUED EXAMINATION (RCE)**  
**TRANSMITTAL FORM (37 C.F.R. § 1.114)**

RECEIVED  
FEB 07 2003  
TC 1700

DOCKET NO. 10191/955	APPLICATION SERIAL NO. 09/238,262	EXAMINER A.K. Alanko	ART UNIT 1746
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INVENTOR(S):  
Joerg SCHAEFER, Peter LINKE, Albrecht SCHWILLE, Helmut BAUMANN

Address to:  
Commissioner for Patents  
Washington D.C. 20231

Attention: Box RCE

I hereby certify that this correspondence is being deposited with the  
United States Postal Service as first class mail in an envelope  
addressed to: Commissioner for Patents, Washington, D.C. 20231,  
on

Date 1/30/03

Signature Catherine Eynard  
KENYON & KENYON

This is a **request for continued examination** under 37 C.F.R. § 1.114 (RCE) of pending application Serial No.09/238,262, filed on January 27, 1999, entitled METHOD OF PRODUCING STRUCTURED WAFERS.

The following constitute the submission **required** by 37 C.F.R. § 1.114(a) and is attached:

☒ Amendment After Final Office Action originally mailed December 6, 2002.  
☐ Information Disclosure Statement 02/06/2003 EAREGAY1 00000122 110600 09238262  
☐ Drawing Changes 01 FC:1801 750.00 CH  
☐ Other Submission: \_\_\_\_\_

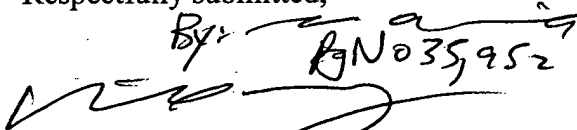
1. The filing fee for this RCE and the required amendment/submission is calculated below. The fee below is calculated based on the status of the claims after the entry of the attached amendment/submission. The fee for any new additional claims is included with this RCE, the fee for previously entered additional claims having already been paid.

	CLAIMS REMAINING AFTER AMENDMENT	MINUS	HIGHEST NUMBER PREVIOUSLY PAID FOR	PRESENT NUMBER EXTRA*	RATE (\$) PER CLAIM	FEE (\$)
BASIC FEE						750.00
TOTAL CLAIMS	11	20	20	0	18.00	0.00
INDEPENDENT CLAIMS	1	3	3	0	84.00	0.00
MULTIPLE DEPENDENT CLAIM					280.00	
				*Number extra must be zero or larger	TOTAL	750.00
	If Applicant is a small entity under 37 C.F.R. §§ 1.9 and 1.27, then divide total fee by 2, and enter amount here.					SMALL ENTITY TOTAL 0.00

2. Please charge the required RCE and submission filing fee of **\$750.00** to the deposit account of **Kenyon & Kenyon**, deposit account number **11-0600**.
3. Applicants request a one month extension of time to respond to the Office Action mailed September 30, 2002, resetting the response date to January 30, 2003. The extension fee of \$110.00 should be charged to the deposit account of **Kenyon & Kenyon**, deposit account number **11-0600**.
4. The Commissioner is hereby authorized to charge payment of fees, including any additional fees required, associated with this communication or arising during the pendency of this application, or to credit any overpayment, to the deposit account of **Kenyon & Kenyon**, deposit account number **11-0600**.
5. A duplicate copy of this transmittal form is enclosed.

Dated: 1/30/03

Respectfully submitted,

By:   
Richard L. Mayer, Reg. No. 22,490



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PATENT TRADEMARK OFFICE

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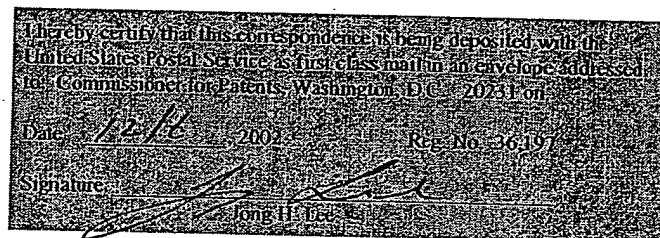
TC 1700

[10191/955]

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x10  
2/29/03IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s) : Joerg SCHAEFER et al.  
Serial No. : 09/238,262  
Filed : January 27, 1999  
For : METHOD OF PRODUCING STRUCTURED WAFERS  
Examiner : Anita Karen Alanko  
Art Unit : 1746

Commissioner for Patents  
Washington, D.C. 20231

AMENDMENT AFTER FINAL OFFICE ACTION

SIR:

In response to the Final Office Action dated September 30, 2002, kindly amend the above-identified application as set forth below. Entry of the amendment is requested since it raises no new issues and puts the claims in condition for allowance and/or in better form for appeal.

IN THE CLAIMS:

Kindly amend claim 14 as follows:

14. (Amended) A method of etching a wafer, comprising the steps of:

providing a wafer having a surface and edge areas;  
dividing the surface of the wafer into positive areas and negative areas, the negative areas including the edge areas of the wafer;

providing the negative areas with a first passivation layer to protect the negative areas from a subsequent second etching process;

providing at least one of the positive areas with a